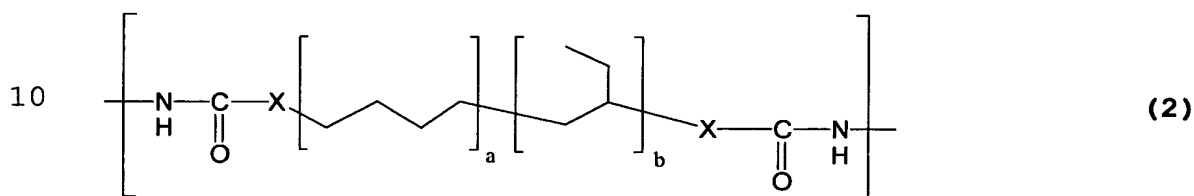
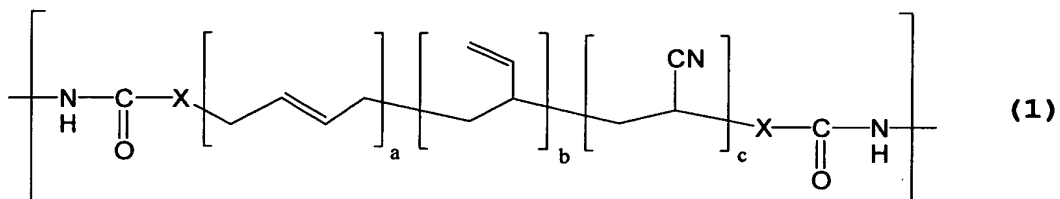
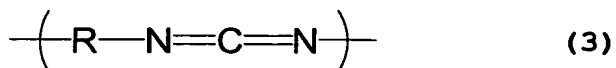


WHAT IS CLAIMED IS:

1. An adhesive film for underfill comprising a polycarbodiimide copolymer which comprises at least one structural unit selected from rubber residues represented by the following formulae (1) and (2) in a number "m":



(wherein each of a, b and c is an integer of from 0 to 200, and X represents an alkylene group having from 0 to 5 carbon atoms) and a structural unit represented by the following formula (3) in a number "n":



(wherein R means an alkyl group having from 4 to 20 carbon atoms or an aryl group) and which comprises on each of the both termini a terminal structural unit derived from a

monoisocyanate, wherein  $m$  is an integer of 2 or more,  $n$  is an integer of 1 or more,  $m + n$  is from 3 to 1,500 and  $m/(m + n)$  is from 1/1,500 to 1/3.

5           2. The adhesive film for underfill according to claim 1, wherein the terminal structural unit of the polycarbodiimide copolymer is a substituted or unsubstituted aryl group, or an alkyl group having 1 to 10 carbon atoms.

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          3. A semiconductor device wherein the space between a semiconductor element and a wiring circuit board is sealed with the adhesive film for underfill according to claim 1.

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          4. A semiconductor device wherein the space between a semiconductor element and a wiring circuit board is sealed with the adhesive film for underfill according to claim 2.

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